10/17/2016 504054050

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT4100714

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Li-Che Chen	06/06/2013
Te-Yuan Wu	06/06/2013
Chia-Huei Lin	06/06/2013
Hui-Min Wu	06/06/2013
Kun-Che Hsieh	06/06/2013
Kuan-Yu Wang	06/06/2013
Chung-Yi Chiu	06/06/2013

RECEIVING PARTY DATA

Name:	UNITED MICROELECTRONICS CORP.
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park
City:	Hsin-Chu City
State/Country:	TAIWAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15295997

CORRESPONDENCE DATA

Fax Number: (703)997-4517

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 3027291562

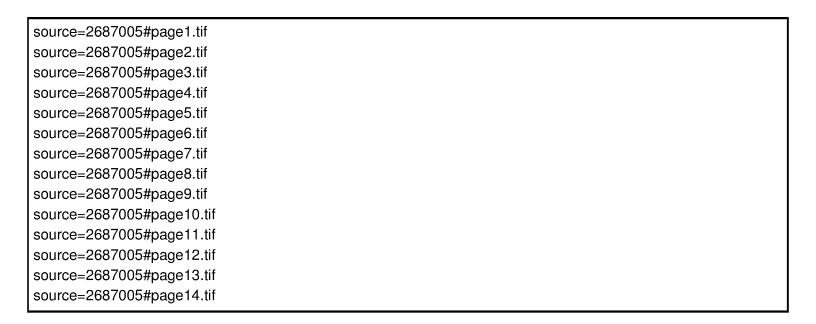
Patent.admin.uspto.cr@naipo.com Email:

WINSTON HSU **Correspondent Name:** Address Line 1: P.O.BOX 506

Address Line 4: MERRIFIELD, VIRGINIA 22116

ATTORNEY DOCKET NUMBER:	NAUP1659USA1
NAME OF SUBMITTER:	SIBYL YU
SIGNATURE:	/SIBYL YU/
DATE SIGNED:	10/17/2016

Total Attachments: 14



Title of Invention: MEMS structure and method of forming the same

As the below named inventor, I herek This declaration is directed to:	by declare that:		
$\ensuremath{\square}$ The attached application, or			
☐ United States application nu	mber	_filed on	, or
☐ PCT international application	number	filed on	· · · · · · · · · · · · · · · · · · ·
The above-identified application was	made or authorized to be made	by me.	
I believe that I am the original invento application.	or or an original joint inventor of	a claimed invention i	n the
I hereby acknowledge that any willful under18 U.S.C. 1001 by fine or impri	false statement made in this de sonment of not more than five (§	claration is punishab 5) years, or both.	ole
In consideration of the payment by	UNITED MICROELECTRO CORP.	NICS having a p	ostal address of
No.3, Li-Hsin Road 2, Science	-Based Industrial Park, Hs	in-Chu City 300,	Taiwan, R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an		00), the receipt of wi	hich is hereby
I hereby sell, assign and transfer to A the entire right, title and interest in ar invention as above-identified applica invention by the above application or substitutes, or extensions thereof, ar	nd to any and all improvements watton and, in and to, all Letters Parany continuations, continuation	vhich are disclosed i itent to be obtained f -in-part, divisions, re	n the for said newals,
I hereby covenant that no assignmer entered into which would conflict with	nt, sale, agreement or encumbra n this assignment;	nce has been or will	be made or
I further covenant that ASSIGNEE wand documents relating to said inver known and accessible to I and will te related thereto and will promptly exe	tion and said Letters Patent and stify as to the same in any interf	l legal equivalents as erence, litigation pro	s may be
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have h	olication, said invention and said ecessary or desirable to carry ou	Letters Patent and s	said
Note: An application data sheet (PT0 inventive entity, must accompany thi	D/SB/14 or equivalent), including s form. Use this form for <u>each a</u>	naming the entire	

Page 1 of 14

Inventor: Li-Che Chen

Date: JUN 0 6 2013

Signature: Li-Che Chen

Page 2 of 14

F#NPO-P0002E-US1201 DSC0-102U003542

NPO#NAU-P1659-USA:0 CUST#UMCD-2013-0088

Title of Invention: MEMS structure and method of forming the same

As the below named inventor, I hereb This declaration is directed to:	by declare that:		
☑ The attached application, or			
☐ United States application nu	mber	filed on	, or
☐ PCT international application	n number	filed on	
The above-identified application was	made or authorized to be made	by me.	
believe that I am the original invento application.	or or an original joint inventor of a	a claimed invention in	the
hereby acknowledge that any willful under18 U.S.C. 1001 by fine or impri			•
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(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an		00), the receipt of which	ch is hereby
I hereby sell, assign and transfer to A the entire right, title and interest in ar invention as above-identified applica invention by the above application or substitutes, or extensions thereof, ar	nd to any and all improvements w tion and, in and to, all Letters Pa any continuations, continuation-	vhich are disclosed in tent to be obtained for in-part, divisions, rene	the r said ewals,
I hereby covenant that no assignmer entered into which would conflict with		nce has been or will b	e made or
I further covenant that ASSIGNEE wand documents relating to said inven known and accessible to I and will te related thereto and will promptly exe	ation and said Letters Patent and estify as to the same in any interfe	legal equivalents as r erence, litigation proce	nay be
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have h	olication, said invention and said ecessary or desirable to carry out	Letters Patent and sa the proposes thereof	id , (Date of signing) -
Note: An application data sheet (PT0 inventive entity, must accompany thi	D/SB/14 or equivalent), including s form. Use this form for <u>each ac</u>	naming the entire	

Page 3 of 14

LEGAL NAME OF INVENTOR(ASSIGNOR)						
Inventor:	Te-Yuar	า Wu		Date:	JUN 0 6 2013	
Signature:	_Te	Yuan	Wu			

Page 4 of 14

NPO#NAU-P1659-USA:0 CUST#UMCD-2013-0088

F#NPO-P0002E-US1201 DSC0-102U003542

MEMS structure and method of forming the same As the below named inventor, I hereby declare that: This declaration is directed to: ☑ The attached application, or ☐ United States application number ______filed on _____, or filed on _____ ☐ PCT international application number The above-identified application was made or authorized to be made by me. I believe that I am the original inventor or an original joint inventor of a claimed invention in the application. I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both. In consideration of the payment by **UNITED MICROELECTRONICS** having a postal address of CORP. No.3, Li-Hsin Road 2, Science-Based Industrial Park, Hsin-Chu City 300, Taiwan, R.O.C. (referred to as "ASSIGNEE" below) to I of the sum of One Dollar (\$ 1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration. I hereby sell, assign and transfer to ASSIGNEE and the successors and assignees of the ASSIGNEE the entire right, title and interest in and to any and all improvements which are disclosed in the invention as above-identified application and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof. I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment; I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof. IN WINTNESS WHEREOF, I have hereunto set hand and seal this JUN 0 6 2013 (Date of signing)

Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.

Page 5 of 14

DSC0-102U003542

Title of Invention:

LEGAL NAME OF INVENTOR(ASSIGNOR)					
Inventor:	Chia-Huei Lin	Date:	JUN 0 6 2013		
Signature:	Cleather Lin				

NPO#NAU-P1659-USA:0 CUST#UMCD-2013-0088 Page 6 of 14

F#NPO-P0002E-US1201 DSC0-102U003542

Title of Invention: MEMS structure and method of forming the same

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☑ The attached application, or				
☐ United States application nu	mber	filed on		, or
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The above-identified application was	made or authorized to be made b	by me.		
I believe that I am the original invento application.	or or an original joint inventor of a	claimed	invention in the	
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In consideration of the payment by	UNITED MICROELECTRON CORP.	IICS	having a posta	l address of
No.3, Li-Hsin Road 2, Science	-Based Industrial Park, Hsi	n-Chu C	City 300, Tai	wan, R.O.C.
(referred to as "ASSIGNEE" below) to acknowledged, and for other good and I hereby sell, assign and transfer to A the entire right, title and interest in an invention as above-identified application or substitutes, or extensions thereof, ar	d valuable consideration. ASSIGNEE and the successors and to any and all improvements witten and, in and to, all Letters Pater any continuations, continuation-in	nd assign hich are o ent to be n-part, di	nees of the ASS disclosed in the obtained for sa visions, renewa	SIGNEE e aid als,
I hereby covenant that no assignmer entered into which would conflict with		ce has be	een or will be n	nade or
I further covenant that ASSIGNEE w and documents relating to said inver known and accessible to I and will te related thereto and will promptly exe	tion and said Letters Patent and I stify as to the same in any interfe	legal equ rence, liti	ivalents as ma	y be
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have h	elication, said invention and said Lacessary or desirable to carry out ereunto set hand and seal this	etters Pa the propo JUN ()	atent and said pses thereof. 6 2013 (D	Date of signing)
Note: An application data sheet (PTC inventive entity, must accompany thi				

Page 7 of 14

LEGAL NAME OF INVENTOR(ASSIGNOR)					
Inventor:	Hui-Min Wu	Date:	JUN 0 6 2013		
Signature:	His - Min We			_	

NPO#NAU-P1659-USA:0 CUST#UMCD-2013-0088 Page 8 of 14

F#NPO-P0002E-US1201 DSC0-102U003542

Title of Invention:

MEMS structure and method of forming the same

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I hereby sell, assign and transfer to a the entire right, title and interest in a invention as above-identified applica invention by the above application of substitutes, or extensions thereof, ar	nd to any and all imp ition and, in and to, a r any continuations, c	rovements which Il Letters Patent continuation-in-p	h are disclosed in to be obtained for art, divisions, rene	the r said ewals,
I hereby covenant that no assignment entered into which would conflict with		r encumbrance	has been or will b	e made or
I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal				
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be no IN WINTNESS WHEREOF, I have h	olication, said inventi- ecessary or desirable	on and said Lett to carry out the	ers Patent and sa	
Note: An application data sheet (PT0 inventive entity, must accompany this				

Page 9 of 14

Inventor: Kun-Che Hsieh

Date: JUN 0 6 2013

Signature: Kun-Che Iskieh

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F#NPO-P0002E-US1201 DSC0-102U003542

NPO#NAU-P1659-USA:0 CUST#UMCD-2013-0088

Title of Invention: MEMS structure and method of forming the same

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I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;					
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representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have h	olication, said invention and said lecessary or desirable to carry out	Letters F the prop	Patent and sai poses thereof.	id (Date of sig	ning)
Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for <u>each additional inventor.</u>					

Page 11 of 14

NPO#NAU-P1659-USA:0 CUST#UMCD-2013-0088

Inventor: Kuan-Yu Wang

Date: JUN 0 6 2013

Signature: Luan - Ju Dang

Page 12 of 14

NPO#NAU-P1659-USA:0 CUST#UMCD-2013-0088 F#NPO-P0002E-US1201 DSC0-102U003542

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I hereby covenant that no assignment entered into which would conflict with	nt, sale, agreement or encumbra h this assignment;	nce has I	oeen or will be	e made or	
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Page 13 of 14

NPO#NAU-P1659-USA:0 CUST#UMCD-2013-0088

LEGAL NA	ME OF INVENTOR(ASSIGNOR)		
inventor:	Chung-Yi Chiu	Date:	JUN 0 6 2013
Signature:	Chung-Yi Chiu		

NPO#NAU-P1659-USA:0 CUST#UMCD-2013-0088 Page 14 of 14

F#NPO-P0002E-US1201 DSC0-102U003542

PATENT REEL: 040035 FRAME: 0803

RECORDED: 10/17/2016